

HSF

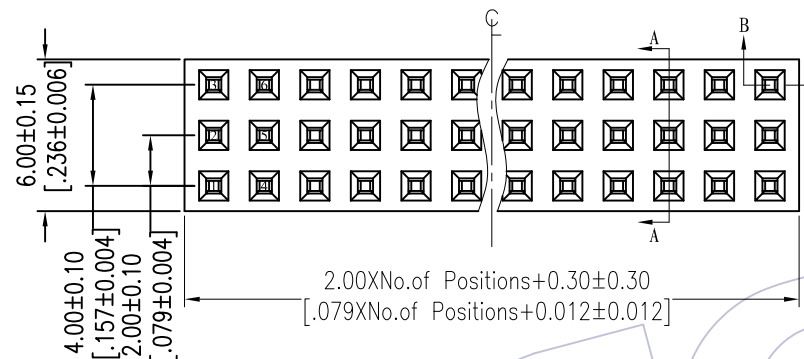
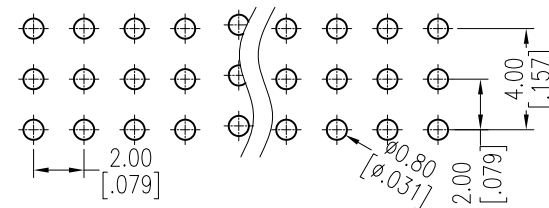
NOTES:

Current Rating: 2.0AMP
Contact Resistance: 20mΩ Max
Withstand Voltage: 500V AC/DC
Insulation Resistance: 1000MΩ Min
Operation Temperature: -40°C to +105°C

Contact Material: Phosphor Bronze
Contact plating: Au Or Sn over Ni
Insulator Material: LCP+30%G.F UL94V-0



Recommended P.C.B Layout(Top Side)
(PCB BOARD TOLERANCE ±0.05)



Ordering Information

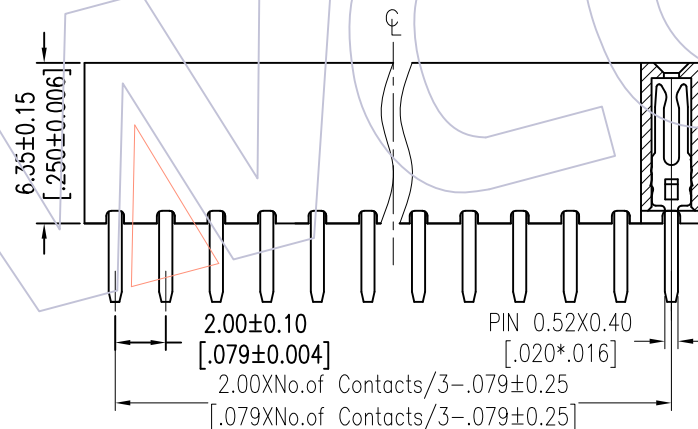
2263 - 3 XX S XX D Y N T X

No. of Pins per
ROW: 02-40 PIN

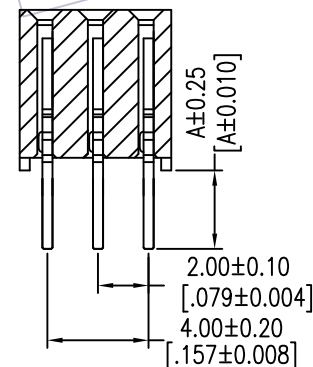
Contact Plating:
G0=Gold Flash
G3=10μ"Gold
G4=15μ"Gold
G5=30μ"Gold
S0=Gold Flash/Tin
S3=10μ"Gold/Tin
S4=15μ"Gold/Tin
S5=30μ"Gold/Tin
SN=Tin
SM=Matte Tin

Insulator:
D=LCP

Packing:
T=Tube



SECTION B-B



SECTION A-A

Item	Pitch	DIM A	Mating
Standard	2.00	3.1/2.4	1215/1220
Alternate			



				OPERATION		DRAW Wang	DATE	SCALE	FIT	PART NO. 2263-3XXSXXDYNTX		
A2	2013/04/26	Modify drawing	-----	X.X	±0.40		2013/04/26	UNIT	mm			
A1	2012/11/07	Modificat the table:DIM A 3.15--3.1/2.4	-----	X.XX	±0.25	CHECK	DATE	SIZE	A4	TITLE: FH2.00mm THREE ROW 180° DIP H=6.35		
A0	2012/07/23	NEW	-----	X.XXX	±0.15			APPROVE	DATE			
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	Angle	± 3'					PROJ.		
				DIM	TOL							